Preface

Dear Distinguished Authors and Guests,

It was a great pleasure to welcome all participants in the 2017 5th International Conference on Metallurgy Technology and Materials (ICMTM 2017) held in Xiamen, China 15-16 April 2017. ICMTM 2017 is dedicated to new research development and advances in the field of Metallurgy, Advanced Materials, Materials processing as well as to other important field i.e simulation and modeling, smart and intelligent system and technology.

The aim of ICMTM 2017 was to present the latest research and results of scientists (professors, students, PhD Students, engineers, and post-doc scientist) related to advanced materials and engineering materials topics. The key goal of the conference provides opportunities for academic scientist, engineer and industry researchers to exchange and share their expertise, experience, new ideas or research result and discuss the challenges and future in their expertise. This conference was also a platform for students, researchers and engineers to interact with experts and specialists on technical matters and future direction of their research area.

The papers were selected after the peer-review process by conference committee member and international reviewers. The submitted papers were selected on the basis of originality, significance, and clarity for the purpose of the conference. The papers provide the reader an overview of many recent advances in the field related to metallurgy, advanced materials, materials processing technologies as well as in other important fields of materials engineering. This conference was also as a platform for the students, researchers and engineers for interaction with experts and specialists on technical matters and future direction of their research area.

On behalf of the organizing committee, I would like to especially thank Jenny Ji (BOSI EDU), Trans Tech Publication, members of organizing committee, reviewers, speakers, chairpersons, sponsors and conference participants for their support and contributions to this volume. We look forward to your participation in the 6th ICMTM in 2018.

With our warmest regards,

Conference Organizing Chair
Assoc. Prof. Zawati Harun
Universiti Tun Hussein Onn Malaysia, Malaysia
May 2017

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